

## Refine Search

### Search Results -

Term	Documents
SEMICONDUCTOR	475614
SEMICONDUCTORS	58752
WAFER	176933
WAFERS	86982
CHIP	336591
CHIPS	181442
PRESSURE	1673786
PRESSURES	309370
SENSITIVE	509273
SENSITIVES	101
ADHESIVE	432634
((((SEMICONDUCTOR (WAFER OR CHIP)) AND (PRESSURE SENSITIVE ADHESIVE (SHEET OR TAPE)) AND ( LOW MOLECULAR WEIGHT NEAR ADHESIVE)).CLM. ).PGPB,USPT.	0

There are more results than shown above. [Click here to view the entire set.](#)

**Database:**

US Pre-Grant Publication Full-Text Database  
 US Patents Full-Text Database  
 US OCR Full-Text Database  
 EPO Abstracts Database  
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 IBM Technical Disclosure Bulletins

**Search:**

L1

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### Search History

**DATE:** Monday, July 11, 2005    [Printable Copy](#)    [Create Case](#)

Set  
**Name Query**

**Hit Set**

side by  
side

Count Name  
result set

*DB=PGPB,USPT; PLUR=YES; OP=ADJ*

L1 ((semiconductor (wafer or chip)) and (pressure sensitive adhesive (sheet or  
tape)) and ( low molecular weight near adhesive)).CLM.

0 L1

END OF SEARCH HISTORY